METHOD OF INCREASING THE AREA OF A USEFUL LAYER OF MATERIAL TRANSFERRED ONTO A SUPPORT

ABSTRACT

The invention relates to a method of increasing the area of a useful layer of material coming from a source substrate and which is effectively transferred onto a support substrate. The dimensions of the outer outline of one of the source and support substrates, referred to as the "first" substrate, are greater than the dimensions of the outer outline of the other substrate, referred to as the "second" substrate. The outer outline of the flat central zone of the first substrate presents dimensions greater than the dimensions of the outer outline of the flat central zone of the second substrate. During bonding, the substrates are applied one against the other in such a manner that the outline of the flat central zone of the second substrate is disposed within the outline of the flat central zone of the first substrate. The invention is applicable, for example, to fabricating a composite substrate product wafer for use in the fields of electronics, optics, or optoelectronics.